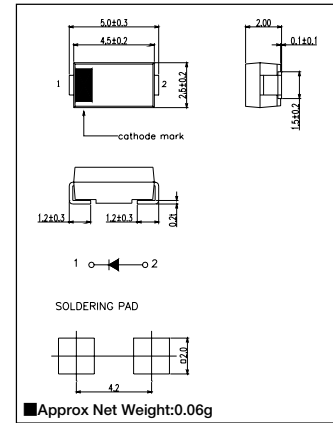


# 1A Avg. 200 Volts Standard Recovery Diode EC10DS2

## ■最大定格 Maximum Ratings

Item	Symbol	Conditions	Unit
くり返しピーク逆電圧 Repetitive Peak Reverse Voltage	$V_{RRM}$	200	V
非くり返しピーク逆電圧 Non-repetitive Peak Reverse Voltage	$V_{RSM}$	400	V
平均整流電流 Average Rectified Forward Current	$I_O$	50Hz, 正弦半波通電抵抗負荷 50Hz Half Sine Wave Resistive Load ( $T_a=25^\circ\text{C}$ )	$0.74^{*1}$
			$1.0^{*2}$
実効順電流 R.M.S. Forward Current	$I_{F(RMS)}$	1.57	A
サージ順電流 Surge Forward Current	$I_{FSM}$	25 50Hz正弦半波, 1サイクル, 非くり返し 50Hz Half Sine Wave, 1cycle, Non-repetitive	A
動作接合温度範囲 Operating Junction Temperature Range	$T_{jw}$	$-40 \sim +150$	$^\circ\text{C}$
保存温度範囲 Storage Temperature Range	$T_{stg}$	$-40 \sim +150$	$^\circ\text{C}$

## ■OUTLINE DRAWING(mm)



## ■電氣的・熱的特性 Electrical/Thermal Characteristics

Item	Symbol	Conditions	Min.	Typ.	Max.	Unit	
ピーク逆電流 Peak Reverse Current	$I_{RM}$	$T_j=25^\circ\text{C}, V_{RM}=V_{RRM}$	—	—	10	$\mu\text{A}$	
ピーク順電圧 Peak Forward Voltage	$V_{FM}$	$T_j=25^\circ\text{C}, I_{FM}=1\text{A}$	—	—	1.1	V	
熱抵抗 Thermal Resistance	$R_{th(j-a)}$	接合部・周囲間 Junction to Ambient	* 1	—	—	157	$^\circ\text{C/W}$
			* 2	—	—	108	$^\circ\text{C/W}$

\*1: プリント基板実装 / Glass Epoxy Substrate mounted (Soldering Land=2×2mm, Both Sides)  
 \*2: アルミナ基板実装 / Alumina Substrate mounted (Soldering Lands= 2 × 2 mm, Both Sides)

## ■定格・特性曲線

